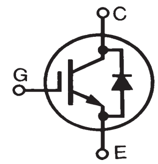
IXYS

GenX3™ 600V IGBT w/ Diode

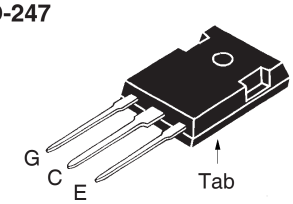
IXGH56N60B3D1

V_{CES} = 600V
I_{C110} = 56A
$V_{CE(sat)}$ ≤ 1.80V

Medium-Speed-Low-Vsat PT IGBT 5-40kHz Switching



TO-247



G = Gate C = Collector
E = Emitter Tab = Collector

Symbol	Test Conditions	Maximum Ratings	
V_{CES}	T_J = 25°C to 150°C	600	V
V_{CGR}	T_J = 25°C to 150°C, R_{GE} = 1MΩ	600	V
V_{GES}	Continuous	±20	V
V_{GEM}	Transient	±30	V
I_{C110}	T_C = 110°C	56	A
I_{CM}	T_C = 25°C, 1ms	350	A
SSOA (RBSOA)	V_{GE} = 15V, T_{VJ} = 125°C, R_G = 5Ω Clamped Inductive Load	I_{CM} = 150 @$V_{CE} \le V_{CES}$	A
P_C	T_C = 25°C	330	W
T_J		-55 ... +150	°C
T_{JM}		150	°C
T_{stg}		-55 ... +150	°C
T_L	Maximum Lead Temperature for Soldering	300	°C
T_{SOLD}	1.6 mm (0.062in.) from Case for 10s	260	°C
M_d	Mounting Torque	1.13/10	Nm/lb.in.
Weight		6	g

Symbol	Test Conditions (T_J = 25°C, Unless Otherwise Specified)	Characteristic Values Min.	Typ.	Max.	
$V_{GE(th)}$	I_C = 250μA, $V_{CE} = V_{GE}$	3.0		5.0	V
I_{CES}	$V_{CE} = V_{CES}$, V_{GE} = 0V			300	μA
	T_J = 125°C			2	mA
I_{GES}	V_{CE} = 0V, V_{GE} = ±20V			±100	nA
$V_{CE(sat)}$	I_C = 44A, V_{GE} = 15V, Note 1		1.49	1.80	V
	T_J = 125°C		1.47		V

Features

- Optimized for Low Conduction and Switching losses
- Square RBSOA
- Anti-Parallel Ultra Fast Diode
- International Standard Package

Advantages

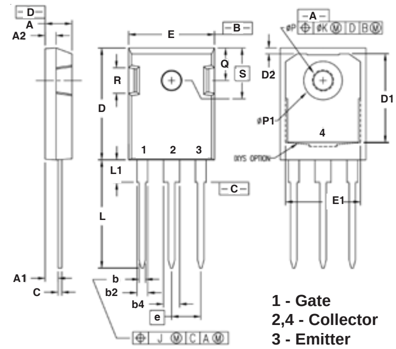
- High Power Density
- Low Gate Drive Requirement

Applications

- Power Inverters
- UPS
- Motor Drives
- SMPS
- PFC Circuits
- Battery Chargers
- Welding Machines
- Lamp Ballasts

Symbol	Test Conditions (T_J = 25°C Unless Otherwise Specified)	Characteristic Values Min.	Typ.	Max.	
g_{fs}	I_C = 44A, V_{CE} = 10V, Note 1	36	60		S
C_{ies}	V_{CE} = 25V, V_{GE} = 0V, f = 1MHz		3950		pF
C_{oes}			220		pF
C_{res}			56		pF
$Q_{g(on)}$	I_C = 40A, V_{GE} = 15V, V_{CE} = 0.5 • V_{CES}		138		nC
Q_{ge}			25		nC
Q_{gc}			47		nC
$t_{d(on)}$	**Inductive Load, T_J = 25°C**		26		ns
t_{ri}	I_C = 44A, V_{GE} = 15V		41		ns
E_{on}	V_{CE} = 480V, R_G = 5Ω		1.30		mJ
$t_{d(off)}$	Note 2		155	335	ns
t_{fi}			95	165	ns
E_{off}			1.05	2.0	mJ
$t_{d(on)}$	**Inductive Load, T_J = 125°C**		26		ns
t_{ri}	I_C = 44A, V_{GE} = 15V		37		ns
E_{on}	V_{CE} = 480V, R_G = 5Ω		2.34		mJ
$t_{d(off)}$	Note 2		220		ns
t_{fi}			165		ns
E_{off}			2.20		mJ
R_{thJC}				0.375	°C/W
R_{thCS}			0.21		°C/W

TO-247 (IXGH) Outline



Dim.	Millimeter min	Millimeter max	Inches min	Inches max
A	4.70	5.30	0.185	0.209
A1	2.21	2.59	0.087	0.102
A2	1.50	2.49	0.059	0.098
b	0.99	1.40	0.039	0.055
b2	1.65	2.39	0.065	0.094
b4	2.59	3.43	0.102	0.135
c	0.38	0.89	0.015	0.035
D	20.79	21.45	0.819	0.845
D1	13.07	-	0.515	-
D2	0.51	1.35	0.020	0.053
E	15.48	16.24	0.610	0.640
E1	13.45	-	0.53	-
E2	4.31	5.48	0.170	0.216
e	5.45 BSC		0.215 BSC	
L	19.80	20.30	0.078	0.800
L1	-	4.49	-	0.177
Ø P	3.55	3.65	0.140	0.144
Ø P1	-	7.39	-	0.290
Q	5.38	6.19	0.212	0.244
S	6.14 BSC		0.242 BSC	

Reverse Diode (FRED)

Symbol	Test Conditions (T_J = 25°C Unless Otherwise Specified)		Characteristic Values Min.	Typ.	Max.	
V_F	I_F = 30A, V_{GE} = 0V, Note 1				2.7	V
		T_J = 150°C		1.6		V
I_{RM}	I_F = 30A, V_{GE} = 0V, -di_F/dt = 100A/μs,	T_J = 100°C			4	A
t_{rr}	V_R = 100V	T_J = 100°C		100		ns
	I_F = 1A, V_{GE} = 0V, -di_F/dt = 100A/μs, V_R = 30V			25		ns
R_{thJC}					0.9	°C/W

Notes:

1. Pulse test, t ≤ 300μs, duty cycle, d ≤ 2%.
2. Switching times & energy losses may increase for higher V_{CE}(clamp), T_J or R_G.

IXYS Reserves the Right to Change Limits, Test Conditions and Dimensions.

Fig. 1. Output Characteristics @ 25ºC

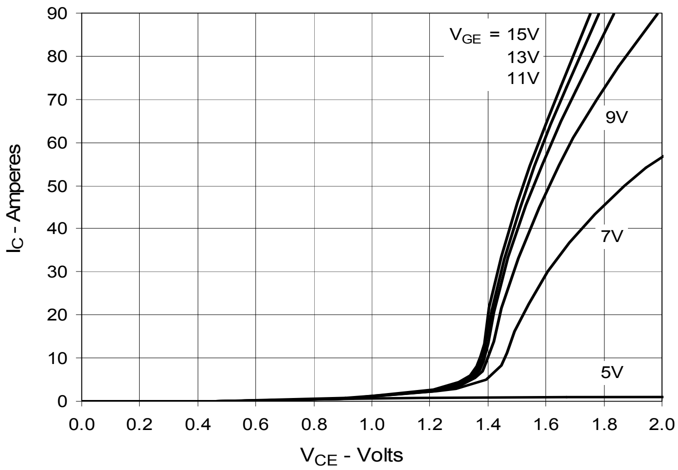


Fig. 2. Extended Output Characteristics @ 25ºC

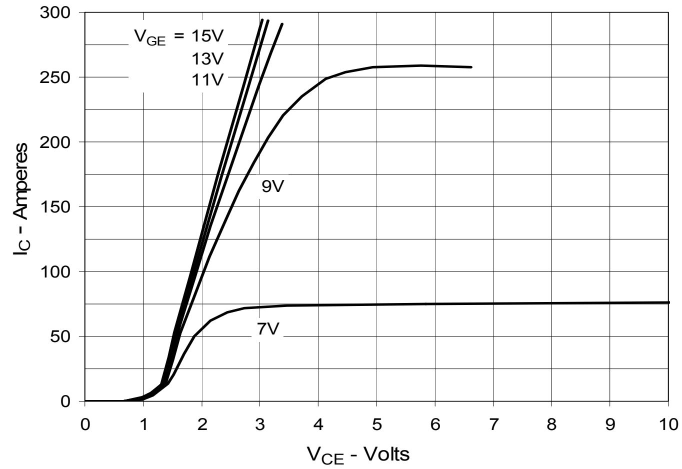


Fig. 3. Output Characteristics @ 125ºC

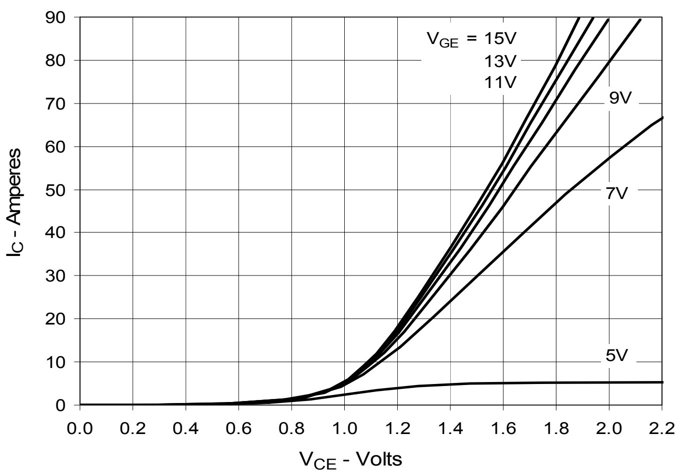


Fig. 4. Dependence of $V_{CE(sat)}$ on Junction Temperature

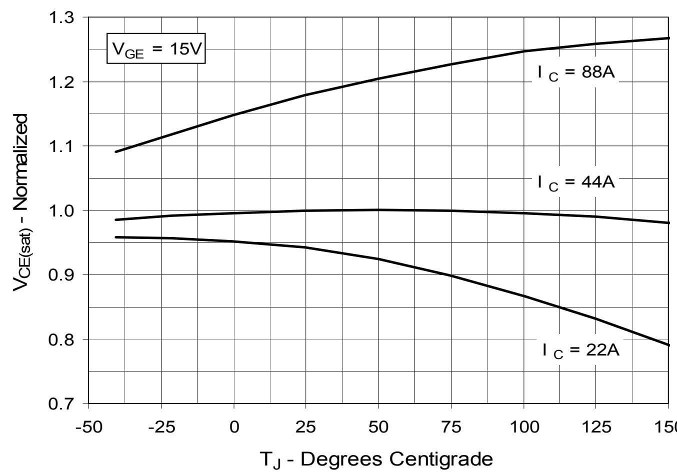


Fig. 5. Collector-to-Emitter Voltage vs. Gate-to-Emitter Voltage

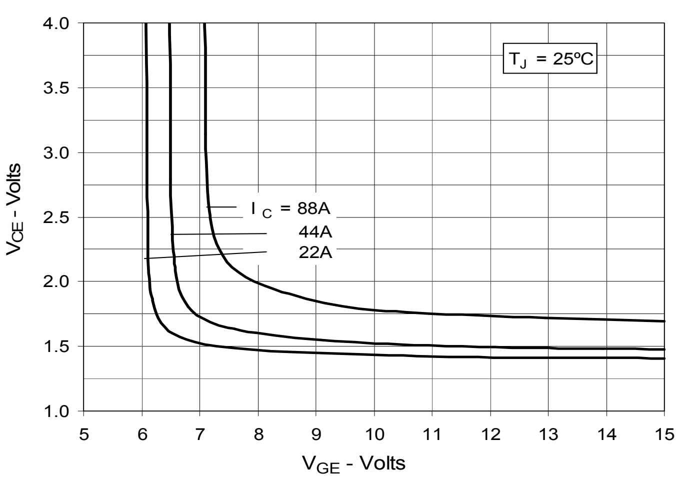


Fig. 6. Input Admittance

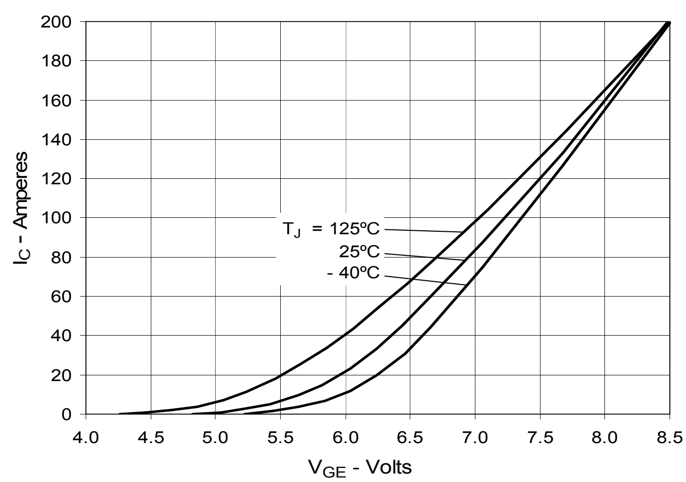


Fig. 7. Transconductance

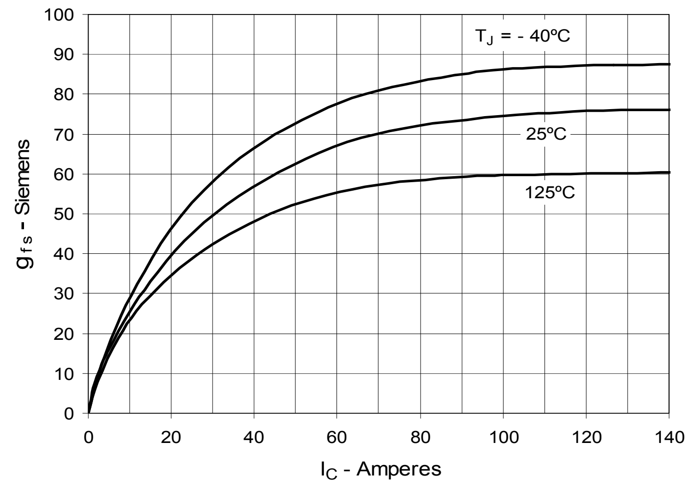


Fig. 8. Gate Charge

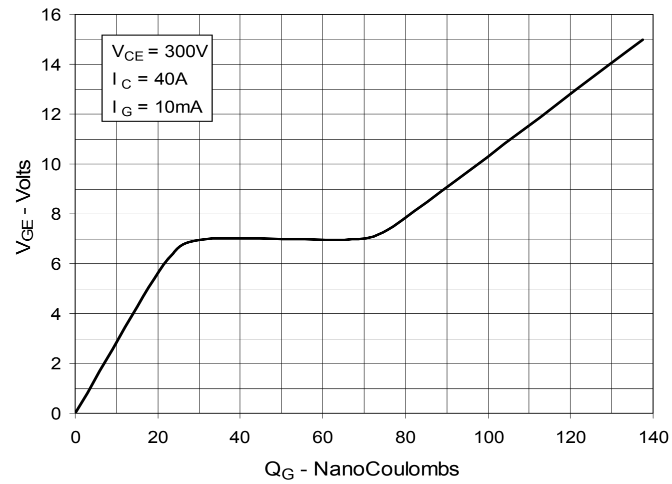


Fig. 9. Capacitance

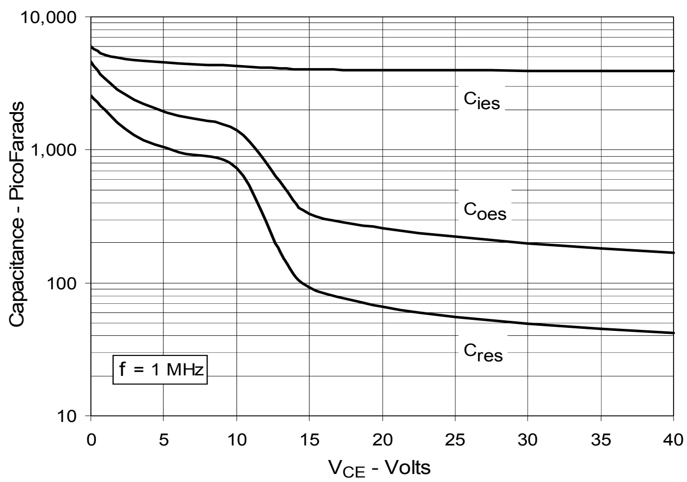


Fig. 10. Reverse-Bias Safe Operating Area

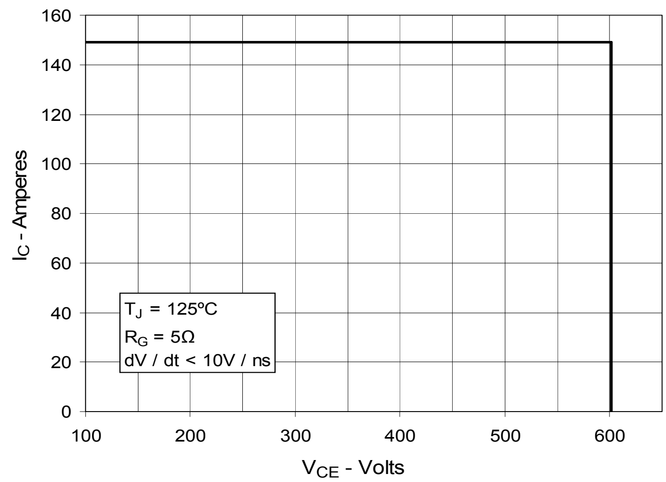


Fig. 11. Maximum Transient Thermal Impedance

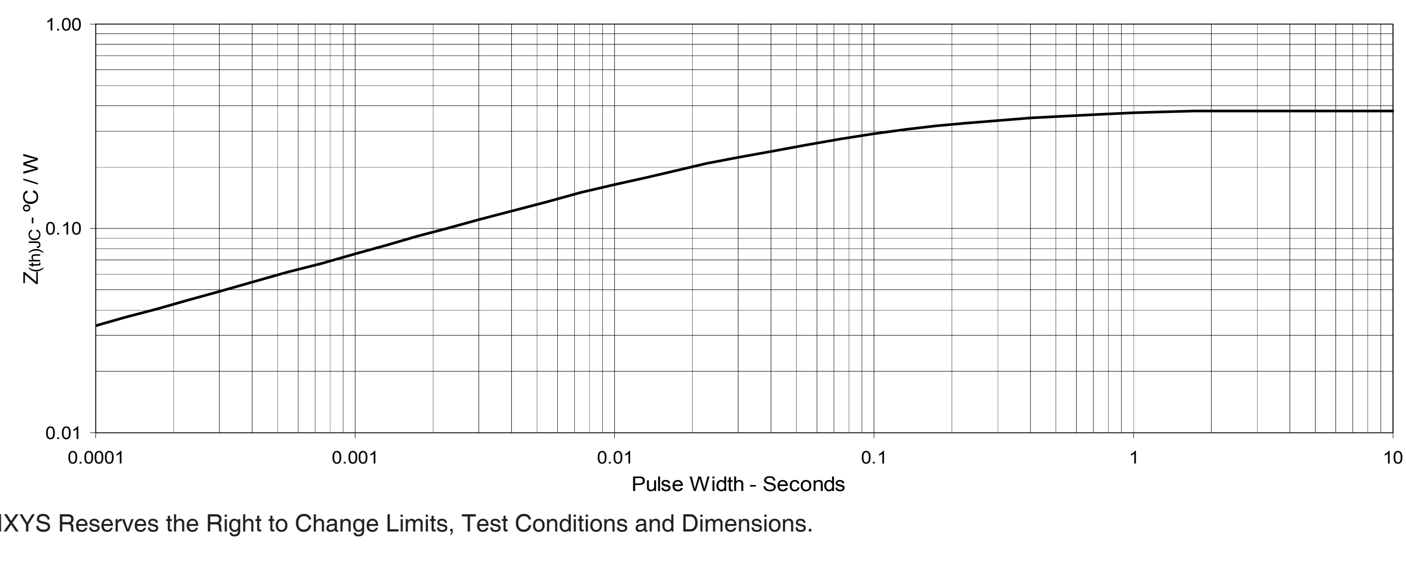


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Fig. 12. Inductive Switching Energy Loss vs. Gate Resistance

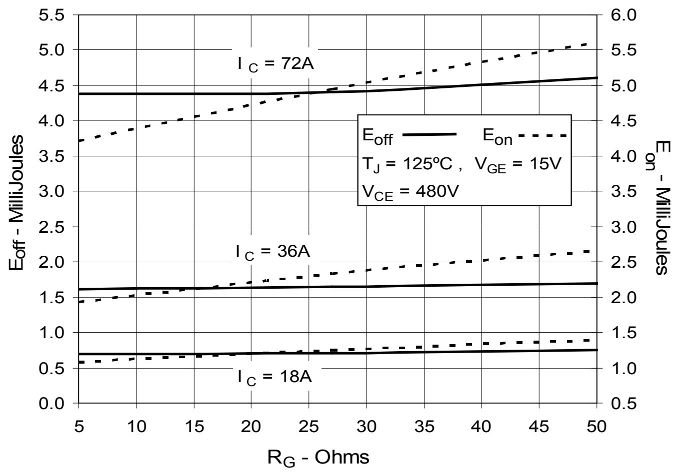


Fig. 13. Inductive Swiching Energy Loss vs. Collector Current

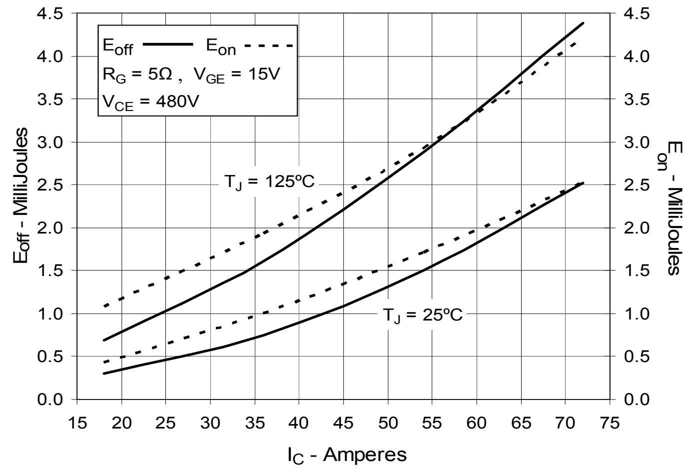


Fig. 14. Inductive Swiching Energy Loss vs. Junction Temperature

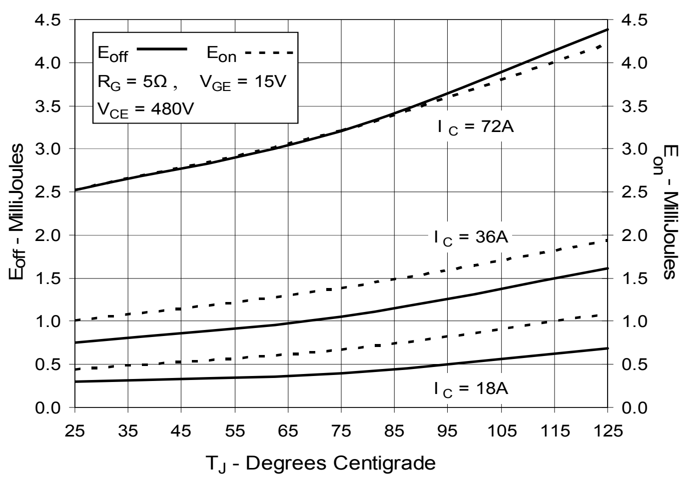


Fig. 15. Inductive Turn-off Switching Times vs. Gate Resistance

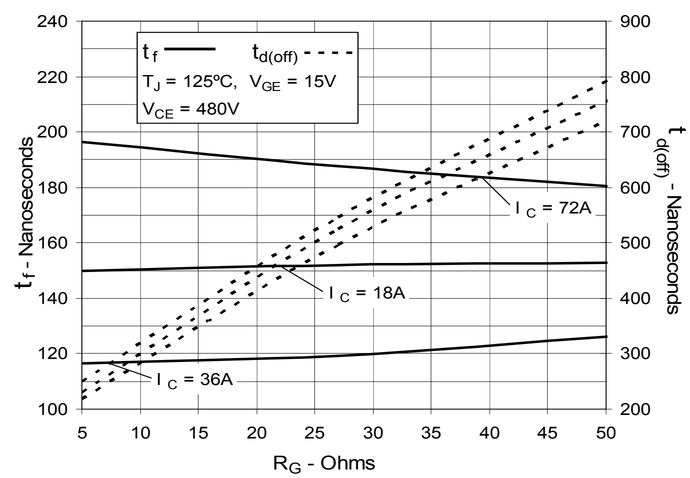


Fig. 16. Inductive Turn-off Switching Times vs. Collector Current

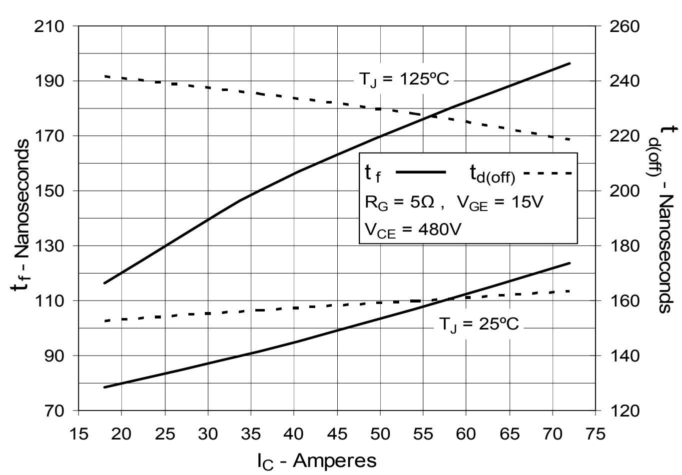


Fig. 17. Inductive Turn-off Switching Times vs. Junction Temperature

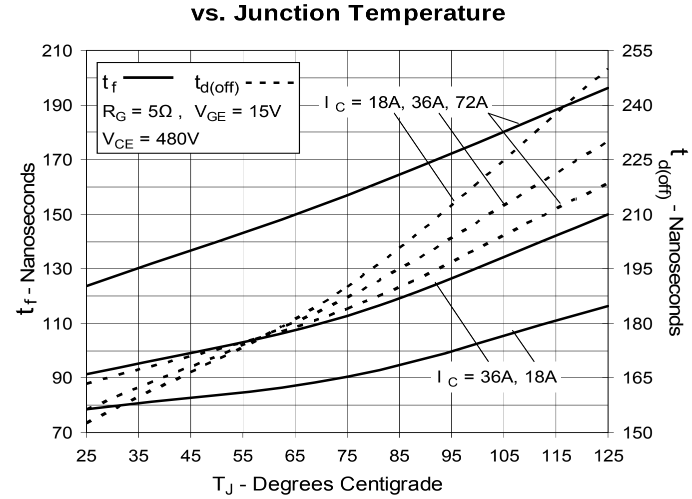


Fig. 18. Inductive Turn-on Switching Times vs. Gate Resistance

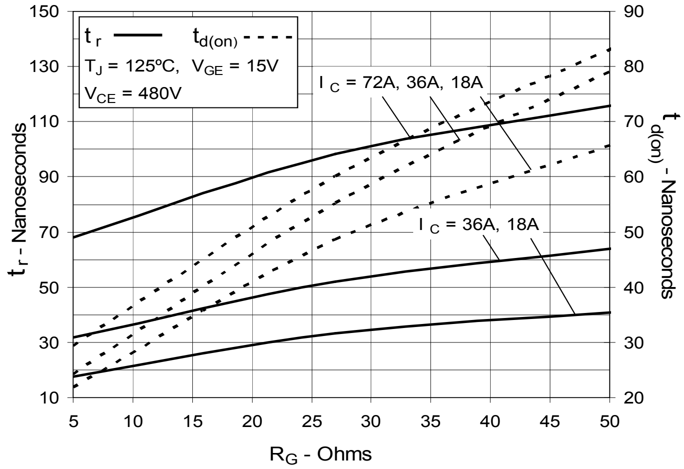


Fig. 19. Inductive Turn-on Switching Times vs. Collector Current

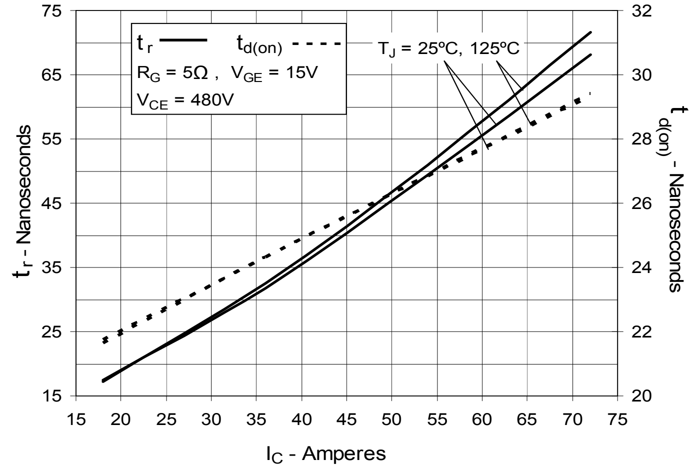
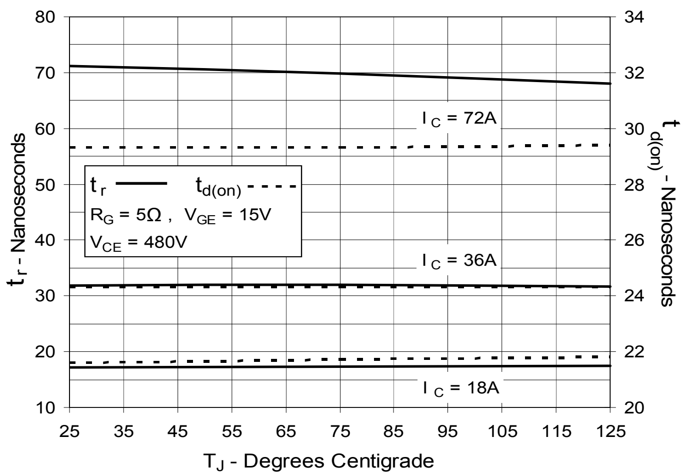


Fig. 20. Inductive Turn-on Switching Times vs. Junction Temperature



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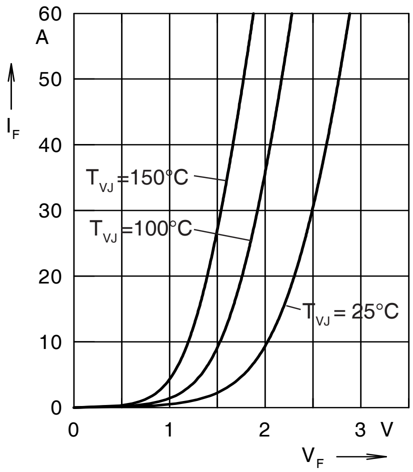

Fig. 21. Forward Current I_F Versus V_F

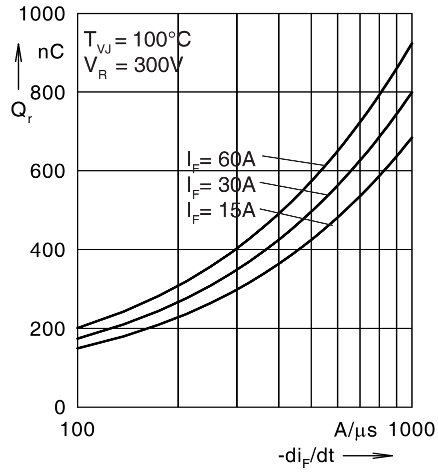

Fig. 22. Reverse Recovery Charge Q_r Versus $-di_F/dt$

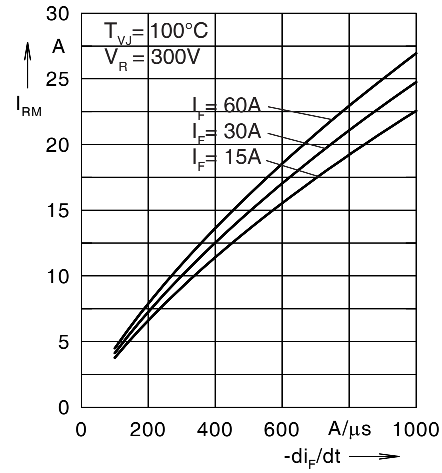

Fig. 23. Peak Reverse Current I_{RM} Versus $-di_F/dt$

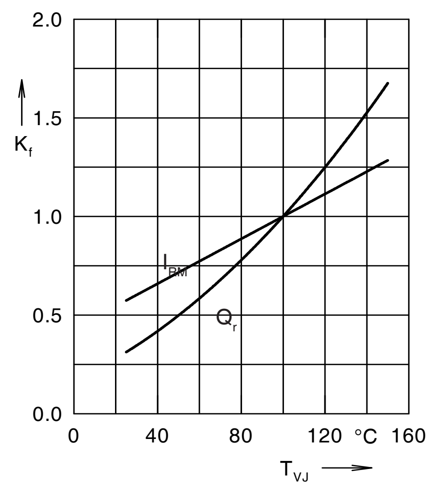

Fig. 24. Dynamic Parameters Q_r, I_{RM} Versus T_{VJ}

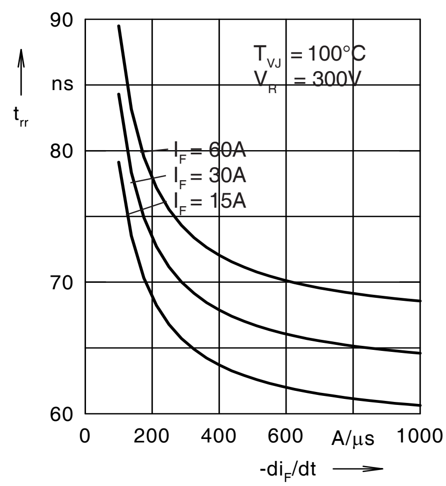

Fig. 25. Recovery Time t_{rr} Versus $-di_F/dt$

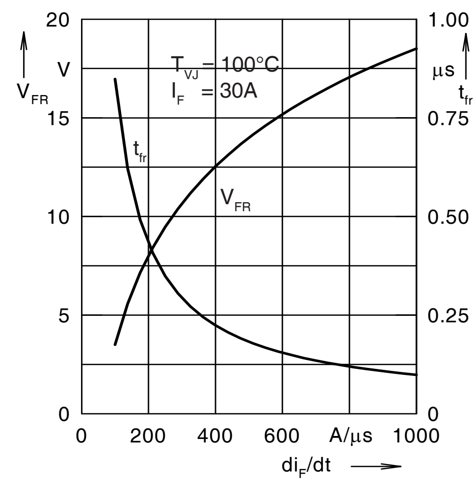

Fig. 26. Peak Forward Voltage V_{FR} and t_{fr} Versus di_F/dt

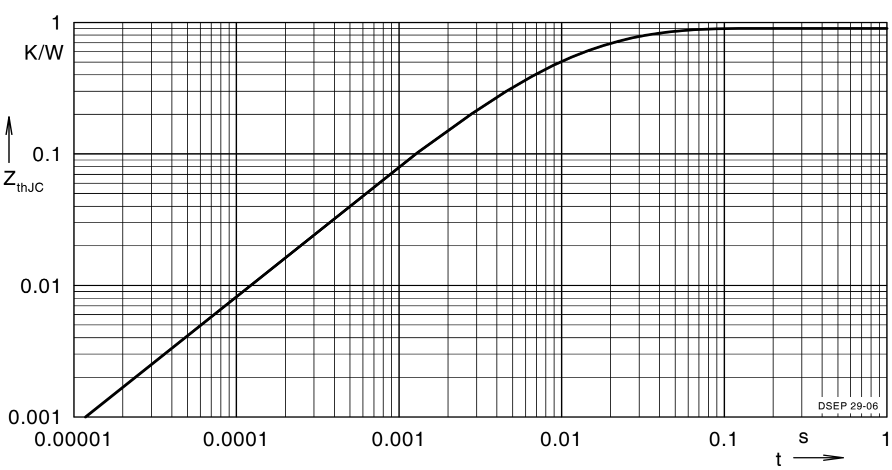

Fig. 27. Transient Thermal Resistance Junction to Case

Constants for Z_{thJC} calculation:

i	R_{thi} (K/W)	t_i (s)
1	0.502	0.0052
2	0.193	0.0003
3	0.205	0.0162